





UC1543, UC1544 UC2543, UC2544 UC3543, UC3544

SLUS188A-APRIL 1997-REVISED FEBRUARY 2007

Power Supply Supervisory Circuit

FEATURES

- Includes Over-Voltage, Under-Voltage, and Current Sensing Circuits
- Internal 1% Accurate Reference
- Programmable Time Delays
- SCR "Crowbar" Drive of 300 mA
- Remote Activation Capability
- Optional Over-Voltage Latch
- Uncommitted Comparator Inputs for Low Voltage Sensing (UC1544 Series Only)

DESCRIPTION

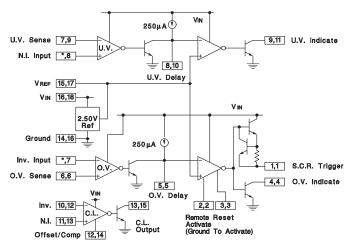
The monolithic integrated circuits contain all the functions necessary to monitor and control the output sophisticated power supply system. Over-voltage (O.V.) sensing with provision to trigger "crowbar" an external SCR shutdown; undervoltage (U.V.) circuit which can be used to monitor either the output or to sample the input line voltage; and a third op amp/comparator usable for current sensing (C.L.) are all included in this device, together with an independent, accurate reference generator.

Both over- and under-voltage sensing circuits can be externally programmed for minimum time duration of fault before triggering. All functions contain open collector outputs which can be used independently or wire-or'ed together, and although the SCR trigger is directly connected only to the over-voltage sensing circuit, it may be optionally activated by any of the other outputs, or from an external signal. The O.V. circuit also includes an optional latch and external reset capability.

The UC1544/2544/3544 devices have the added versatility of completely uncommitted inputs to the voltage sensing comparators so that levels less than 2.5 V may be monitored by dividing down the internal reference voltage. The current sense circuit may be used with external compensation as a linear amplifier or as a highgain comparator. Although nominally set for zero input offset, a fixed threshold may be added with an external resistor. Instead of current limiting, this circuit may also be used as an additional voltage monitor.

The reference generator circuit is internally trimmed to eliminate the need for external potentiometers and the entire circuit may be powered directly from either the output being monitored or from a separate bias voltage.

BLOCK DIAGRAM



NOTE:

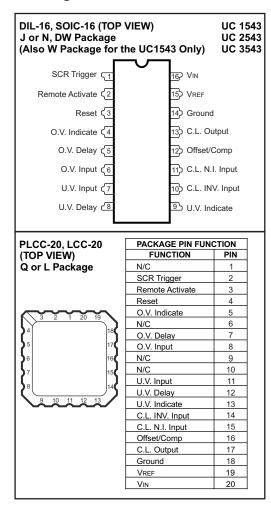
For each terminal, first number refers to 1543 series, second to 1544 series. *On 1543 series, this function is internally connected to VREF.

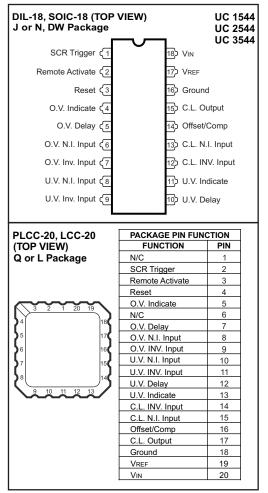


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Connection Diagrams





ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			VALUE	UNIT
V _{IN}	Input supply voltage		40	V
	Sense inputs, voltage range		0 to VIN	V
	SCR trigger current (2)		-600	mA
	Indicator output voltage		40	V
	Indicator output sink current		50	mA
	Power dissipation (package limita	ition)	1000	mW
	Operating temperature range	UC1543, UC1544	-55 to 125	
T _J		UC2543, UC2544	-25 to 85	°C
		UC3543, UC3544	0 to 70	
T _{stg}	Storage temperature range		-65 to 150	

- (1) Currents are positive-into, negative-out of the specified terminal.
- (2) At higher input voltages, a dissipation limiting resistor, RG, is required.



ELECTRICAL CHARACTERISTICS

Unless otherwise stated, these specifications apply for T_A = -55°C to 125°C for theUC1543 and UC1544; -25°C to 85°C for the UC2543 and UC2544; and 0°C to 70°C for the UC3543 and UC3544. Electrical tests are performed with V_{IN} = 10 V and 2-k Ω pull-up resistors on all indicator outputs. All electrical specifications for the UC1544, UC2544, and UC3544 devices are tested with the inverting over-voltage input and the non-inverting under-voltage input externallyconnected to the 2.5 V reference. T_A = T_J .

	PARAMETER	TEST CONDITIONS	UC1543/UC1544/UC2543/ UC2544			UC3543/UC3544			UNIT	
			MIN TYP		MAX	MIN	TYP	MAX		
\/	lanut valtaga ranga	$T_J = 25^{\circ}C$ to T_{MAX}	4.5		40	4.5		40	V	
V_{IN}	Input voltage range	T _{MIN} to T _{MAX}	4.7		40	4.7		40	ľ	
I _{CC}	Supply current	$V_{IN} = 40 \text{ V, output open,}$ $T_J = 25^{\circ}\text{C}$		7	10		7	10	mA	
		$T_{MIN} \le T_J \le T_{MAX}$			15			15		
Refere	ence Section									
V	Output voltage	$T_J = 25^{\circ}C$	2.48	2.5	2.52	2.45	2.50	2.55	— V	
V _{OUT}		Over temperature range	2.45		2.55	2.40		2.60		
	Line regulation	V _{IN} = 5 to 30 V		1	5		1	5	\/	
	Load regulation	I _{REF} = 0 to 10 mA		1	10		1	10	mV	
	Short circuit current	V _{REF} = 0	-10	-20	-40	-12	-20	-40	mA	
	Temperature stability			50			50		ppm/°C	
SCR T	rigger Section			•	•	•				
	Peak output current	V _{IN} = 5V, RG = 0, VO = 0	-100	-300	-600	-100	-300	-600	mA	
	Peak output voltage	V _{IN} = 15 V, I _O = -100 mA	12	13		12	13		.,	
	Output OFF voltage	V _{IN} = 40 V		0	0.1		0	0.1	V	
	Remote activate current	R/A Pin = GND		-0.4	-0.8		-0.4	-0.8	mA	
	Remote activate voltage	R/A Pin Open		2	6		2	6	V	
	Reset current	Reset = GND, R/A = GND		-0.4	-0.8		-0.4	-0.8	mA	
	Reset voltage	Reset open, R/A = GND		2	6		2	6	V	
	Output current rise time	$R_L = 50, T_J = 25^{\circ}C, C_D = 0$		400			400		mA/μs	
	Prop. delay from R/A	$R_L = 50, T_J = 25^{\circ}C, C_D = 0$		300			300			
	Prop. delay from O/V input	$R_L = 50, T_J = 25^{\circ}C, C_D = 0$		500			500		ns	
Compa	arator Section	-				"				
	Input threshold (Input	$T_J = 25^{\circ}C$	2.45	2.50	2.55	2.40	2.50	2.60		
	voltage rising on O.V. and falling on U.V.)	Over temperature range	2.40		2.60	2.35		2.65	V	
	Input hysteresis			25			25		mV	
	Input bias current	Sense input = 0 V		-0.3	-1.0		-0.3	-1.0	μΑ	
	Delay saturation			0.2	0.5		0.2	0.5	V	
	Delay high level			6	7		6	7	v	
	Delay charging current	$V_O = 0$	-200	-250	-300	-200	-250	-300	μΑ	
	Indicate saturation	I _L = 10 mA		0.2	0.5		0.2	0.5	V	
	Indicate leakage	V _{IND} = 40 V		0.01	1.0		0.01	1.0	μΑ	
	Propagation delay	Input over drive = 200 mV, $T_J = 25$ °C, $C_D = 0$		400			400		ns	
	Propagation delay	Input over drive = 200 mV, $T_J = 25$ °C, $C_D = 1 \mu F$		10			10		ms	

ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise stated, these specifications apply for $T_A = -55^{\circ}\text{C}$ to 125°C for the UC1543 and UC1544; -25°C to 85°C for the UC2543 and UC2544; and 0°C to 70°C for the UC3543 and UC3544. Electrical tests are performed with $V_{\text{IN}} = 10 \text{ V}$ and 2-k Ω pull-up resistors on all indicator outputs. All electrical specifications for the UC1544, UC2544, and UC3544 devices are tested with the inverting over-voltage input and the non-inverting under-voltage input externallyconnected to the 2.5 V reference. $T_A = T_J$.

urrent Limit Section									
Input voltage range		0		VIN -3V	0		VIN -3V	V	
Input Bias Current	Offset pin open, V _{CM} = 0		-0.3	-1.0		-0.3	-1.0	μΑ	
land offert value	Offset pin open, V _{CM} = 0		0	10		0	10	\/	
Input offset voltage	10k from offset pin to GND	80	100	120	80	100	120	120 mV	
CMRR	CMRR $0 \le V_{CM} \le 12 \text{ V}, V_{IN} = 15 \text{ V}$		70		60	70			
AVOL	Offset pin open, V_{CM} = 0 V , R_L = 10 $k\Omega$ to 15 $k\Omega$, V_{OUT} = 1 to 6 V	72	80		72	80		dB	
Output saturation	Output saturation I _L = 10 mA		0.2	0.5		0.2	0.5	V	
Output leakage	V _{IND} = 40 V		0.01	1.0		0.01	1.0	μΑ	
Small signal bandwidth	$A_V = 0$ dB, $T_J = 25$ °C		5			5		MHz	
Propagation delay	$V_{OVERDRIVE} = 100 \text{ mV},$ $T_J = 25^{\circ}\text{C}$		200			200		ns	

TYPICAL CHARACTERISTICS

Recommended Series Gate Resistance, Rg For Use With Higher Supply Voltages 200 Rg > Vin -5 0.2 PB 0 5 10 15 20 25 30 35 40 Vin SUPPLY VOLTAGE - (VOLTS) Figure 1.

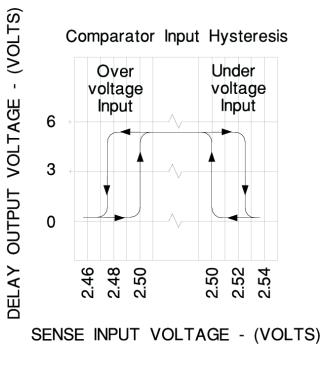
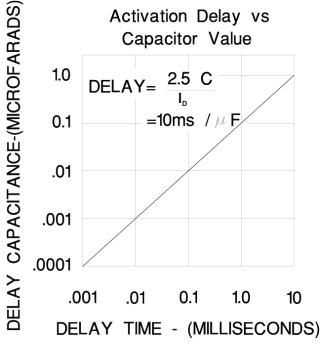


Figure 2.





Current Limit Input Threshold

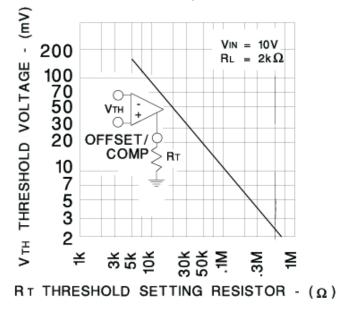


Figure 3.

Current Limit Amplifier Gain

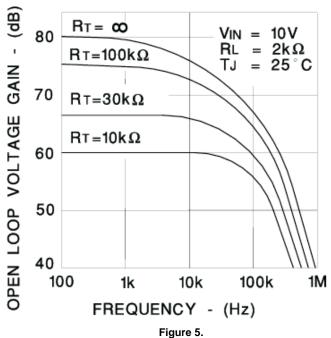


Figure 4.

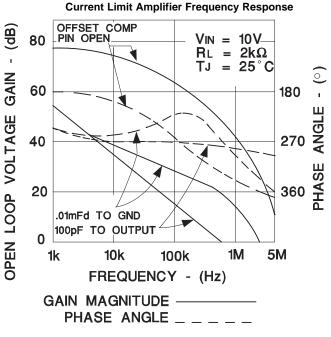


Figure 6.

APPLICATION INFORMATION

The values for the external components are determined as follows:

$$V_{TH} = \frac{1000}{R1}$$

Current limit input threshold,

C_S is determined by the current loop dynamics

$$I_P \cong \frac{V_{TH}}{R_{SC}} + \frac{V_O}{R_{SC}} \left(\frac{R2}{R2 + R3} \right)$$

Peak current to load.

$$I_{SC} = \frac{V_{TH}}{R_{SC}}$$

Short circuit current,

$$V_{O(low)} = \frac{2.5(\,R4 + R5 + R6\,)}{R5 + R6} \label{eq:Volume}$$
 Low output voltage limit,

$$V_{O(high)} = \frac{2.5(R4 + R5 + R6)}{R6}$$

High output voltage limit.

Voltage sensing delay, $t_D = 10,000C_d$

$$R_G > \frac{V_{IN} - 5}{0.2}$$

SCR trigger power limiting resistor,

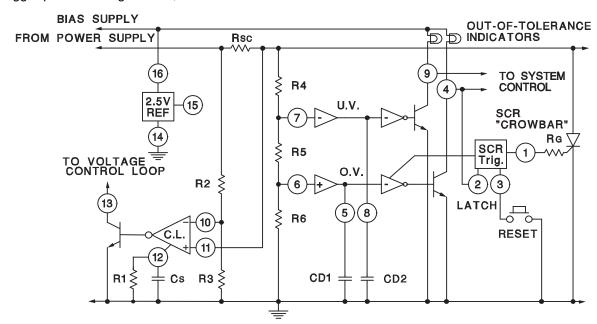


Figure 7. Typical Application



APPLICATION INFORMATION (continued)

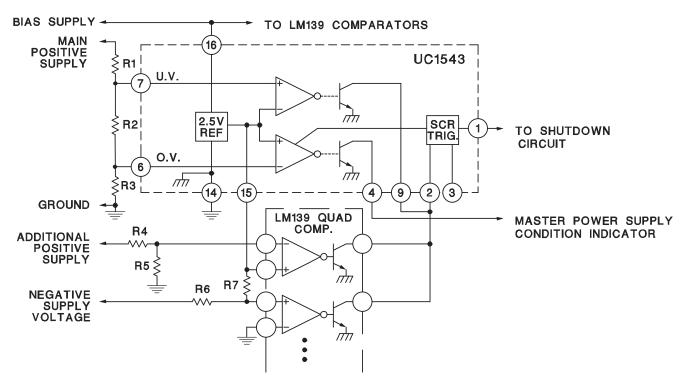


Figure 8. Sensing Multiple Supply Voltages

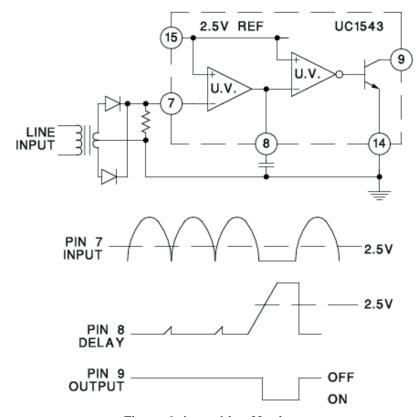


Figure 9. Input Line Monitor

APPLICATION INFORMATION (continued)

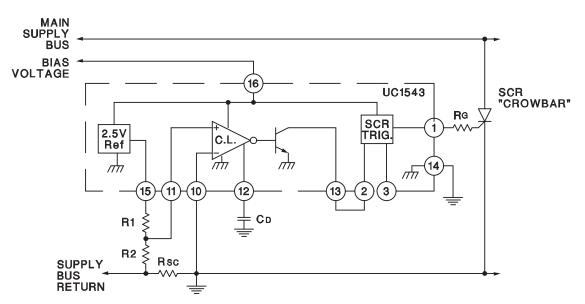


Figure 10. Overcurrent Shutdown







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
5962-8774001EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8774001FA	ACTIVE	CFP	W	16	25	TBD	A42 SNPB	N / A for Pkg Type
5962-8774002VA	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI
UC1543J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1543J883B	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1543L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC1543L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC1543W883B	ACTIVE	CFP	W	16	25	TBD	A42 SNPB	N / A for Pkg Type
UC1544J	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI
UC1544J883B	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI
UC1544L	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
UC1544L883B	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
UC2543DW	NRND	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2543DWG4	NRND	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2543J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC2543N	NRND	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2543NG4	NRND	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2544DW	NRND	SOIC	DW	18	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2544DWG4	NRND	SOIC	DW	18	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2544J	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI
UC2544N	NRND	PDIP	N	18	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2544NG4	NRND	PDIP	N	18	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3543DW	NRND	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3543DWG4	NRND	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3543J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC3543N	NRND	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3543NG4	NRND	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3544J	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI
UC3544N	NRND	PDIP	N	18	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3544NG4	NRND	PDIP	N	18	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.



PACKAGE OPTION ADDENDUM

2-Dec-2008

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

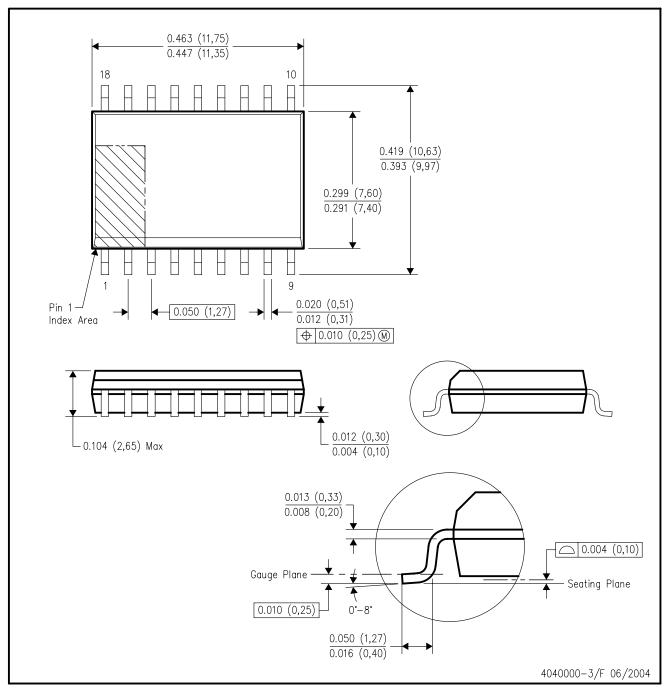


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



DW (R-PDSO-G18)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AB.



DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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